

## AMENDMENTS

### In the Specification:

**On Page 3, please amend the Paragraph starting at line 25 and ending at line 28 by substituting the following:**

B1  
Figs. 1 and 2 depict elevational section views of the prior art microstrip line 1 and strip line 5 monolithic constructions respectively. Both of these constructions are well known in the planar fabrication and microcircuit technology. In Fig. 1, the strip line comprises a metal conductor 2 etched on top of an insulator 4, which in turn rests on a layer of conductor 3.

**On Page 3, please amend the Paragraph starting at line 30 and ending at Page 4, line 2, by substituting the following:**

B2  
The stripline construction 5 shown in Fig. 2 comprises a pair of metal conductors 6 and 8 in spaced apart positions with one of the conductors 9 embedded within the insulation material 7. In both of these constructions, the only way to achieve field isolation is to space adjacent conductors apart. However, this uses an undesirable amount of surface area on the substrate to achieve such isolation.

**On Page 5, please amend the Paragraph starting at line 13 by substituting the following:**

38 Each of the other of the conductive layers 10 between the one of the conductive layers 16 and the top one of the conductive planes 14, and between the one of the conductive layers 16 and the bottom one of the conductive planes 12, comprises a pair of laterally spaced apart conductive strips separated by a nonconductive spacer layer 42 so that the pair of laterally spaced conductive strips are spaced approximately at the selected width, i.e., the stack width 32. Each of the nonconductive separator layers 20 provides a plurality of vias 22 filled with conductive material 50 conductively joining the two outermost 16', 16''' of the three conductive strips of the one of the conductive layers 16, and the spaced apart conductive strips of the other of the conductive layers 10, and the conductive planes 12, 14 so as to form a conductive sidewall shield about the centermost 16'' of the three laterally spaced apart conductive strips.

**On Page 7, please amend the Paragraph starting at line 13 by substituting the following:**

34 The process further comprises the step of extending, by simple metal deposition, the initial 12 and the final 14 ones of conductive layers, as the top and the bottom conductive planes, to define the mutually registered selected width 32 of the stack 30.